THAT 300 Series

FEATURES

- 4 Matched NPN Transistors (300)
 - 4 Matched PNP Transistors (320)
 - 2 Matched NPNs and PNPs (340)
 - 4 Matched NP6N 4 Matched PNP (380)
- Monolithic Construction
- Low Noise
 - $0.75 \, nV/\sqrt{Hz} \, (PNP)$
 - $0.8 \, \text{nV} / \sqrt{\text{Hz}} \, (\text{NPN})$
- High Speed
 - $f_T = 350 \text{ MHz (NPN)}$ $f_T = 325 \text{ MHz (PNP)}$
- Excellent Matching 500 μV typical between devices of same gender
- Dielectrically Isolated
- $36V V_{\text{CEO}}$

APPLICATIONS

- Microphone Preamplifiers
- **Current Sources**
- **Current Mirrors**
- Log/Antilog Amplifiers
- Multipliers
- Servos

DESCRIPTION

The THAT300 Series ICs are large-geometry monolithic NPN and/or PNP transistor arrays which combine low noise, high speed and excellent parametric matching between devices of the same gender. The large geometries typically result in 25 Ω base spreading resistance for the PNP devices (30 Ω for the NPNs), producing $0.75 \, nV/\sqrt{Hz}$ voltage noise $(0.8 \text{ nV}/\sqrt{\text{Hz}} \text{ for the NPNs})$. This makes the 300 Series an ideal choice for low-noise amplifier input

Fabricated on a Complementary Bipolar Dielectrically Isolated process, each transistor is electri-

cally isolated from the others by a layer of insulating oxide. The resulting low collector-to-substrate capacitance produces a typical NPN f_T of 350 MHz, 325 MHz for the PNPs. This delivers ac performance similar to discrete 2N3904- and 2N3906-class devices. Dielectric isolation also minimizes crosstalk and provides complete DC isolation.

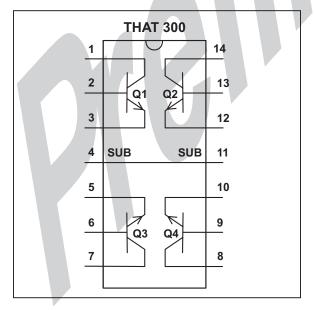
Substrate biasing is not required for normal operation, though the substrate should be grounded to optimize speed and minimize inter-device crosstalk. The monolithic construction assures excellent parameter matching and tracking over temperature.

Part Number	Configuration	Package
THAT300P	4 Mataka d NIDNI Turansiatana	DIP14
THAT300S	4-Matched NPN Transistors	SO14
THAT320P	4. Match ad DND Transistans	DIP14
THAT320S	4- Matched PNP Transistors	SO14
THAT340P	2 Matched NPN Transistors and	DIP14
THAT340S	2 Matched PNP Transistors	SO14
THAT380G	4 Matched NPN Transistors and 4 Matched PNP Transistors	Individual Die

Table 1. Ordering Info

SPECIFICATIONS 1

Maximum Ratings (T _A = 25°C)							
Parameter	Symbol	Conditions	Mi	n Typ	Max	Units	
NPN Collector-Emitter Voltage	BV_CEO	$I_C = 1 \text{ mAdc}, I_B = 0$	36	3 40	_	V	
NPN Collector-Base Voltage	BV_CBO	$I_C = 10 \mu Adc, I_E = 0$	36	3 40	_	V	
NPN Emitter-Base Voltage	BV_{EBO}	$I_{E} = 100 \ \mu Adc, \ I_{C} = 0$	5	_		V	
NPN Collector Current	I _{C MAX}		10	20		mA	
NPN Emitter Current	I _{E MAX}		10	20		mA	
PNP Collector-Emitter Voltage	BV _{CEO}	$I_C = 1 \text{ mAdc}, I_B = 0$	-3	6 –40		V	
PNP Collector-Base Voltage	BV_CBO	$I_{C} = 10 \mu Adc, I_{E} = 0$	-3	6 –40		V	
PNP Emitter-Base Voltage	BV_{EBO}	$I_{E} = 100 \ \mu Adc, \ I_{C} = 0$	_5	j		V	
PNP Collector Current	I _{C MAX}		-1	0 –20		mA	
PNP Emitter Current	I _{E MAX}		-1	0 –20		mA	
Collector-Collector Voltage	BV _{CC}		±10	00 ±200	_	V	
Emitter-Emitter Voltage	BV _{EE}		±10	00 ±200	_	V	
Operating Temperature Range	T _A		0		70	°C	
Maximum Junction Temperature	T_JMAX				150	°C	
Storage Temperature	T _{STORE}		-4:	5	125	°C	





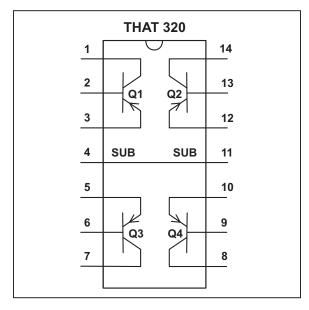
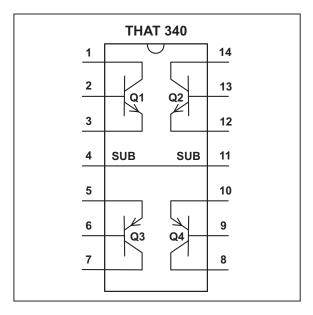


Fig 2. 320 Pinout

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SPECIFICATIONS¹ (Cont'd)



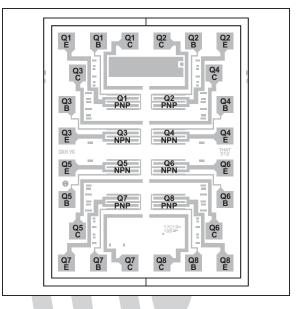


Fig 3. 340 Pinout

Fig 4. 380 Die layout

NPN Electrical Characteristics ²							
Parameter	Symbol	Conditions	Min	Тур	Max	Units	
NPN Current Gain	h _{fe}	V _{CB} = 10 V					
		I _C = 1 mA	60	100	_		
		I _C = 10 μA		100	_		
NPN Current Gain Matching	Δh_{fe}	V _{CB} = 10 V, I _C = 1 mA	_	5	_	%	
NPN Noise Voltage Density	e _N	$V_{CB} = 10 \text{ V}, I_{C} = 1 \text{ mA}, 1 \text{ kHz}$	_	0.8	_	nV/√Hz	
NPN Gain-Bandwidth Product	f _T	$I_{C} = 1 \text{ mA}, V_{CB} = 10 \text{ V}$		350		MHz	
NPN ΔV _{BE} (THAT300: V _{BE1} -V _{BE2} ,\	/ _{BE3} -V _{BE4}) (1	ГНАТ340: V _{BE1} -V _{BE2})					
	Vos	$I_C = 1 \text{ mA}$	_	±0.5	±3	mV	
		I _C = 10 μA	_	±0.5		mV	
NPN ΔI _B (THAT300: I _{B1} -I _{B2} , I _{B3} -I _{B4})) (THAT340	: I _{B1} -V _{B2})					
	Ios	I _C = 1 mA	_	±500	±1500	nA	
		$I_C = 10 \mu A$	_	±5		nA	
NPN Collector-Base Leakage Cur	rent I _{CBO}	V _{CB} = 25 V	_	25	_	рА	
NPN Bulk Resistance	r _{BE} \	$V_{CB} = 0 \text{ V}, 10 \mu\text{A} < I_{C} < 10 \text{mA}$	_	2	_	Ω	
NPN Base Spreading Resistance	r_{bb}	V_{CB} = 10 V, I_{C} = 1 mA	_	30	_	Ω	
NPN Collector Saturation Voltage	V _{CE(SAT)}	$I_C = 1 \text{ mA}, I_B = 100 \mu\text{A}$	_	0.05		V	
NPN Output Capacitance	C _{OB} V	_{CB} = 10 V, I _E = 0 mA, 100 kHz		3		pF	
NPN Collector-CollectorCapacitar	nce (THAT3 C _{CC}	00: Q1-Q2, Q3-Q4) (THAT340: V _{CC} = 0 V, 100 kHz	Q1-Q2)	0.7		pF	

^{1.} All specifications subject to change without notice.

^{2.} Unless otherwise noted, $T_A\!=\!25^{\circ}\!\text{C}.$

SPECIFICATIONS¹ (Cont'd)

Parameter	PNP Electrical Characteristics ²					
	Symbol	Conditions	Min	Тур	Max	Units
PNP Current Gain	h_{fe}	V _{CB} = 10 V				
		$I_C = 1 \text{ mA}$	50	75	- 4	
		I _C = 10 μA		75	- 1	
PNP Current Gain Matching	Δh_{fe}	V_{CB} = 10 V, I_{C} = 1 mA	_	5	_	%
PNP Noise Voltage Density	e _N	V_{CB} = 10 V, I_{C} = 1 mA, 1 kHz	_	0.75		nV/√H:
PNP Gain-Bandwidth Product	f_{T}	I_{C} = 1 mA, V_{CB} = 10 V		325		MHz
PNP ΔV_{BE} (THAT320: V_{BE1} - V_{BE2} ;	V _{BE3} -V _{BE4}) (THAT340: V _{BE3} -V _{BE4})				
	V_{OS}	I _C = 1 mA	_ /	±0.5	±3	mV
		I _C = 10 μA	-1/	±0.5		mV
PNP ΔI _B (THAT320: I _{B1} -I _{B2;} I _{B3} -I _{B4}) (THAT340	: I _{B3} -I _{B4})				
	I_{OS}	I _C = 1 mA	—	±700	±1800	nA
		I _C = 10 μA		±7		νΑ
PNP Collector-Base						
Leakage Current	I _{CBO}	V _{CB} = 25 V		-25	_	pA
PNP Bulk Resistance	r _{BE}	$V_{CB} = 0 \text{ V}, 10\mu\text{A} < I_{C} < 10 \text{ mA}$		2	_	Ω
PNP Base Spreading Resistance	e r _{bb}	V _{CB} = 10 V, I _C = 1 mA	1	25	_	Ω
PNP Collector Saturation Voltage	e V _{CE(SAT)}	$I_C = 1 \text{ mA}, I_B = 100 \mu\text{A}$		-0.05		V
PNP Output Capacitance	Сов	V _{CB} = 10 V, I _E = 0 mA, 100 kHz		3		pF
PNP Collector-Collector Capacit	ance (THAT	320: Q1-Q2; Q3-Q4) (THAT340:	Q3-Q4)			
	C _{CC}	$V_{CC} = 0 \text{ V}, 100 \text{ kHz}$		0.6		pF

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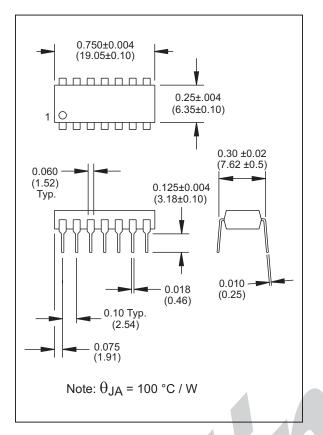
CAUTION: THIS IS AN ESD (ELECTROSTATIC DISCHARGE) SENSITIVE DEVICE.

It can be damaged by the currents generated by electrostatic discharge. Static charge and therefore dangerous voltages can accumulate and discharge without detection causing a loss of function or performance to occur.

The transistors in this device are unprotected in order to maximize performance and flexibility. They are more sensitive to ESD damage than many other ICs which include protection devices at their inputs. Note that all of the pins (not just the "inputs") are susceptible.

Use ESD preventative measures when storing and handling this device. Unused devices should be stored in conductive packaging. Packaging should be discharged to the destination socket before the devices are removed. ESD damage can occur to these devices even after they are installed in a board-level assembly. Circuits should include specific and appropriate ESD protection.

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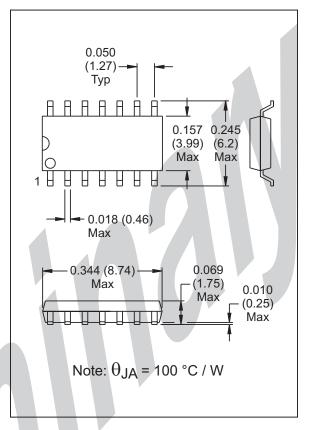


Figure 5. Dual-In-Line Package Outline

Figure 6. Surface-Mount Package Outline

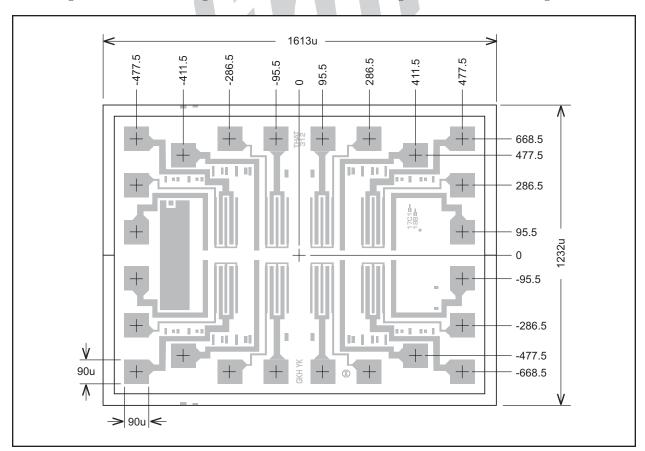


Figure 7. Die dimensions